

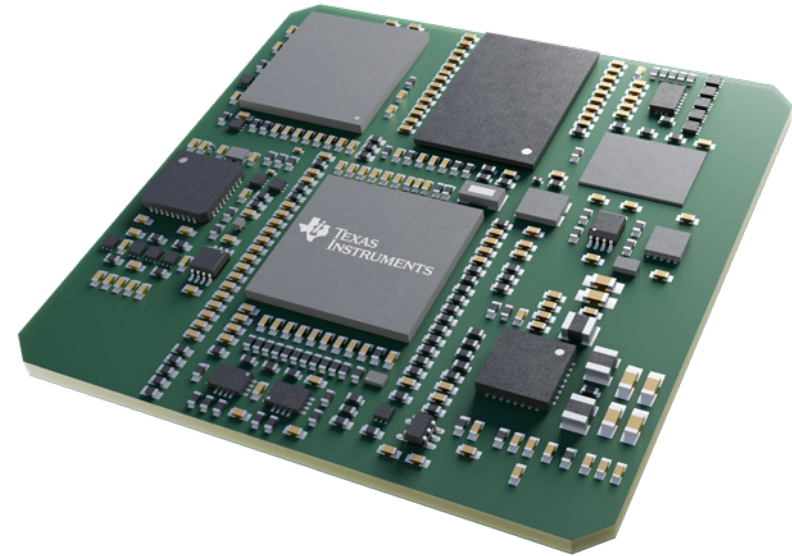
Embedded Module with TI AM62

Open Standard Module™ - iesy AM62 OSM-LF

Technical Concept

- ▶ Processor: AM6231 Single-Core A53 (no 3D GPU) + Cortex-M4F MCU
- ▶ CPU Clock-Rate: 800 MHz (A53) / 400 MHz (M4F)
- ▶ RAM: 512 MByte LPDDR4
- ▶ Flash-Memory: 8 GByte e-MMC 5.1
- ▶ Dimension: 45 mm x 45 mm
- ▶ Footprint: OSM Size-L
Land Grid Array (LGA) with 662 contacts
- ▶ Supply: Single Supply 5VDC
- ▶ Temperature range: 0 °C to +85 °C

- ▶ Features & Interfaces
 - > 2x Ethernet 1 GBit (RGMII)
 - > 1x USB 2.0 (Client/Host/OTG)
 - > 1x MIPI CSI (4 Lanes, I2C)
 - > 1x RGB (18bit) - optional
 - > 1x Dual-LVDS (I2C)
 - > 1x SD-Card + 1x SDIO (4bit)
 - > 37x GPIO (incl. PRU-Signals)
 - > 2x CAN
 - > 1x I2S
 - > 2x I2C
 - > 1x Quad-SPI + 2x SPI
 - > 3x UART + 1x Debug-UART



About OSM™

The Open Standard Modules™ specification was adopted by the SGeT e.V. in 2019. The new standard was developed to meet future requirements in terms of **flexibility**, **scalability**, but also **costs**. OSM™ solder-down modules can be **individually adapted** to the respective customer requirements. For this purpose, the individual modules can be made **available to the SMT process** by means of tray & reel packaging and processed automatically. The OSM™ series includes in total four different form factors.



iesy.com/osm